

EPEPS 2024 Call for Papers

33rd IEEE Conference on Electrical Performance of Electronic Packaging and Systems

October 6-9, 2024, Toronto, Canada, www.epeps.org

EPEPS is the *premier international conference* on advanced and emerging issues in the electrical modeling, analysis, and design of electronic interconnections, packages, and systems. Over four days, the conference will feature the latest advancements in modeling, design, and measurement techniques for:

- signal integrity & power integrity
- advanced packaging and heterogeneous integration
- performance optimization

of systems for high-speed electronics, RF and wireless communication, and quantum computing.

Highlights & reasons to attend

- **top-notch 4-day [program](#)**, with keynotes, presentations, posters and demo sessions focused on the latest advancements from academia and industry
- **four prestigious [awards](#)** for the best contributions
- a full day of **tutorials**
- **industry exhibition and demos**
- **[sponsorship & exhibitor opportunities](#)** to promote your company's latest developments and increase your brand visibility to a specialized audience from the top companies and universities in the field
- **[Toronto](#)** is the fastest growing tech hub in North America, home of a talent pool of 400,000+ post-secondary students, and one of the most vibrant and multicultural cities in the world
- visit **[Canada](#)** in its most spectacular season, with Fall colors in full swing and the Niagara Falls only 1.5 hours away!

Call for papers

We welcome new and unpublished contributions in the following [areas](#)

Interconnects design & technologies	Packaging and integration
<ul style="list-style-type: none">▪ High-speed channels, backplanes, SerDes, memory, DDR interfaces	<ul style="list-style-type: none">▪ Advanced packaging, 3D integration▪ Heterogeneous integration

<ul style="list-style-type: none"> ▪ Interconnect and transceiver co-design, equalization ▪ Signal & power integrity issues ▪ Jitter, noise ▪ High-frequency interconnects, packages, antennas-in-package ▪ Novel/unconventional interconnect technologies <p>Manufacturing and measurement</p> <ul style="list-style-type: none"> ▪ Manufacturing, testing, reliability ▪ Measurement techniques 	<ul style="list-style-type: none"> ▪ Design of interconnects and packages ▪ Quantum systems: interconnection & packaging aspects <p>Modeling and simulation</p> <ul style="list-style-type: none"> ▪ Modeling, simulation, computer-aided design ▪ Thermal, mechanical, multiphysics modeling ▪ ML and AI-based approaches to interconnect and packaging problems
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Important dates

- **Paper submission:** June 14, 2024 ([see template and instructions here](#))
- **Acceptance:** end of July 2024
- **Sponsor registration:** August 6th, 2024
- **Early bird registration:** September 6th, 2024